

# BRCS3139WB

Rev.A Oct.-2025

## / Descriptions

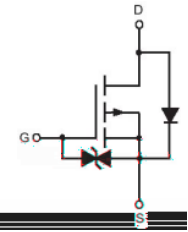
SOT-523 P MOS  
P-CHANNEL MOSFET in a SOT-523 Plastic Package.

## / Features

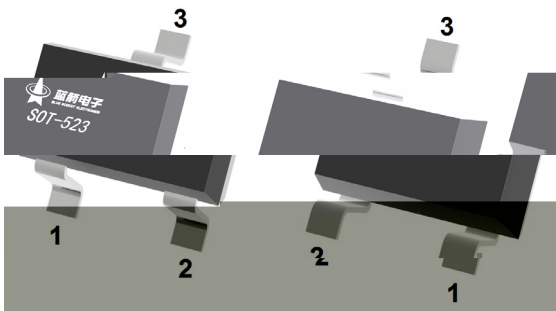
## / Applications

Load Switching, Low Current Inverters, Low Current DC/DC Converters.

## / Equivalent Circuit



## / Pinning



PIN 1 G      PIN 2 S      PIN 3 D

## / Marking

See Marking Instructions.



**/ Electrical Characteristic Curve**

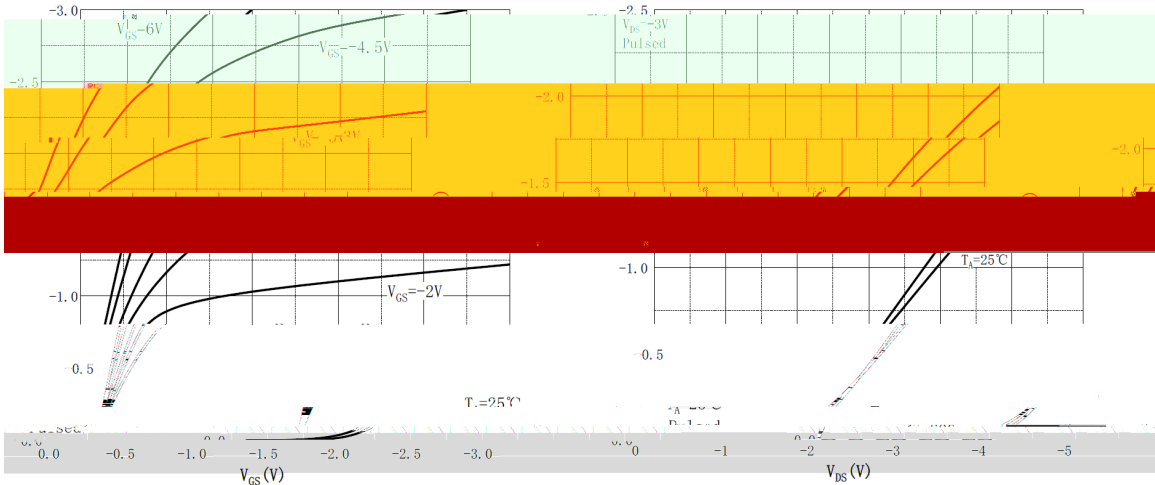


Figure 2. Transfer Characteristics

Figure 1. Output Characteristics

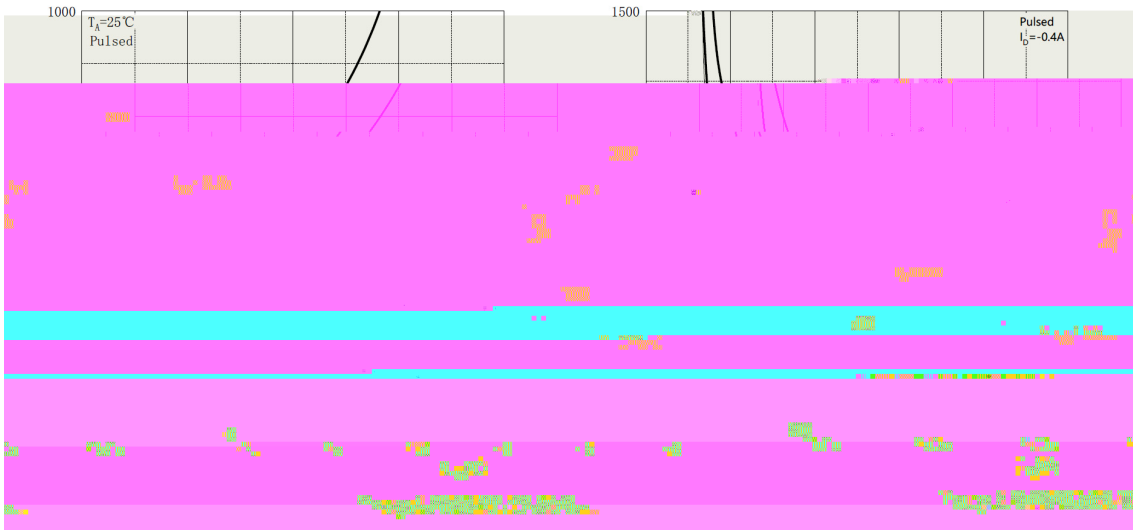


Figure 3. Threshold Voltage

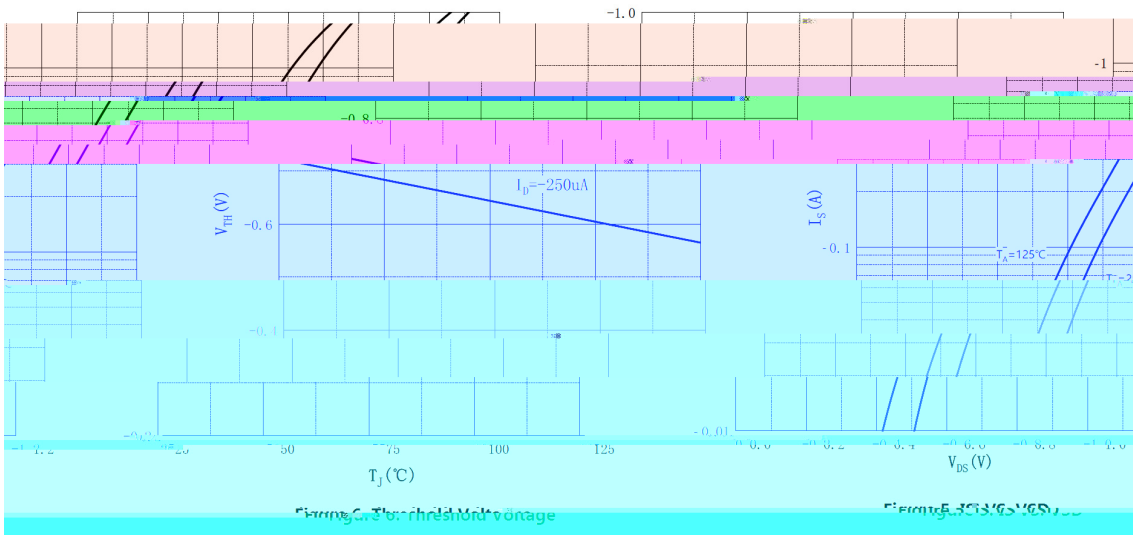
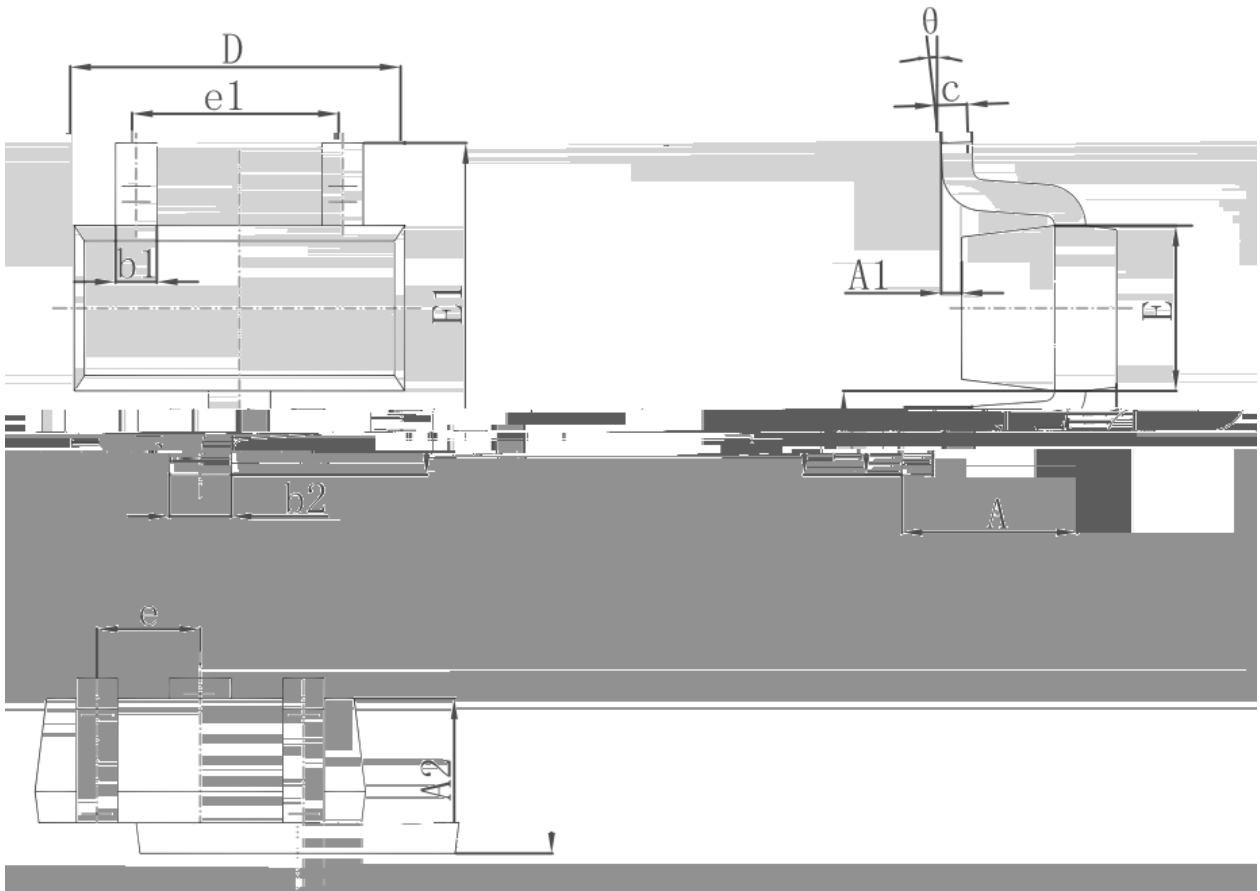


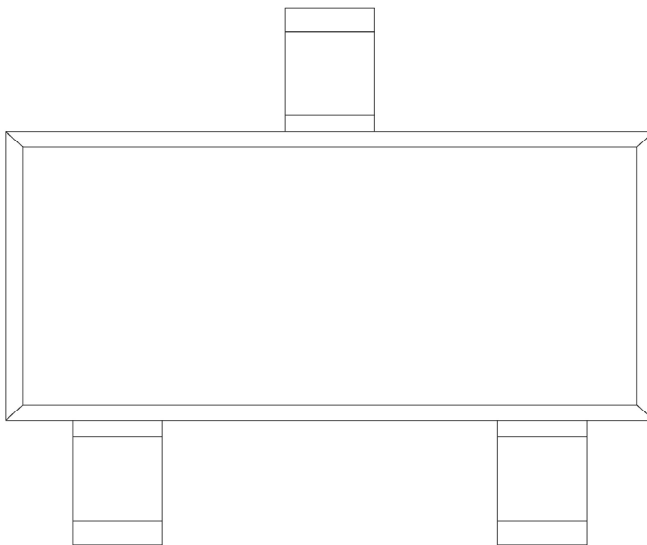
Figure 5. Output Characteristics

**/ Package Dimensions**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	0.700	0.900	0.028	0.035	
A1	0.000	0.100	0.000	0.004	
A2	0.700	0.800	0.028	0.031	
b1	0.250	0.350	0.010	0.014	
b2	0.200	0.004	0.008	0.100	
c	1.700	0.059	0.067	D	1.500
D	0.900	0.028	0.035	E	0.700
E	1.750	0.057	0.069	E1	1.450
e	TYP.	0.020 TYP.		e	0.500
e1	1.100	0.035	0.043	e1	0.900
L	REF.	0.016 REF.		L	0.400
L1	0.460	0.010	0.018	L1	0.260
theta	8°	0°	8°	theta	0°

**/ Marking Instructions**



39K

**( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


**Note:**

- |   |     |     |    |          |   |
|---|-----|-----|----|----------|---|
| 1 | 150 | 180 | 60 | 90sec;   | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245 | 5   | 5  | 0.5sec;  | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 |     |     | 2  | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

**/ Resistance to Soldering Heat Test Conditions**

260 5                      10 1 sec.                      Temp.:260±5                      Time:10±1 sec

**/ Packaging SPEC.**

**/ REEL**

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
	/	/	/	/	/			